WHAT IS CLAIMED IS:

1. A force distributor configured for disposition between a printed circuit board and a stiffening plate, which is spaced from the printed circuit board, to distribute a compressive force between the printed circuit board, an interposer and a land grid array module carried on a side of the printed circuit board opposite the stiffening plate, the force distributor comprising:

a spring element defining a curved member comprising a first portion and a second portion with the first portion extending radially outward from the second portion and configured for placement so that the first portion is secured to the stiffening plate and the second portion is biased in unsecured pressing contact against the printed circuit board.

2. The force distributor of claim 1 wherein the second portion of the force distributor comprises a central body portion and the first portion comprises a plurality of legs extending outward from the central body portion with an end of each leg configured for secure mounting on the stiffening plate,

wherein the central body portion and legs are configured and sized to cause forcible compressive contact from the central body portion against a central area of the printed circuit board.

3. An electronic component system comprising:

a land grid array module;

a printed circuit board having a first side and a second side;

an interposer disposed between the module and the first side of the printed circuit board;

a backing plate spaced from, and disposed on the second side of the printed circuit board opposite the first side;

a plurality of posts extending through and connecting each of module, the printed circuit board, the interposer, and the backing plate relative to each other; and

a curved spring member disposed between the backing plate and the second side of the printed circuit board, and having a first portion in secured contact with the backing plate and a second portion in unsecured, pressing contact against the second side of the printed circuit board adjacent a center of the printed circuit board.

4. The system of claim 3 wherein the second portion of the spring member comprises a central body portion and the first portion of the spring member comprises a plurality of leg members radially extending outward from the central body portion with an end of each leg member including a hole configured for receiving one of the posts to secure the spring member relative to the backing plate.

5. The system of claim 4 wherein the legs and the central body portion are configured with a curved shape so that a convexity of the spring member faces the second side of the printed wired board.

6. The system of claim 5 wherein the spring member includes the hole of each leg member having an elongate shape configured to permit limited sliding movement of each leg of the spring member relative to each of the posts.

7. The system of claim 3 wherein the central body portion defines a body of material formed without holes.

8. The system of claim 3 wherein the backing plate includes a recessed portion defined in a main body of the backing plate that is configured to receive the ends of the spring member.

9. The system of claim 8 wherein the recessed portion has a width less than a width of the main body and has a length less than a length of the main body, and the spring member is sized and shaped to be removably secured within the recessed portion of the backing plate.

10. The system of claim 3 wherein the spring member is a single member that provides the substantially all of the compressive clamping force on the system.

11. A force distributing mechanism comprising:

means for securing a land grid array module and a printed circuit board in electrical communication with each other including introducing a contact force between an array of contact elements of the land grid array module and an array of contact elements of the printed circuit board; and

means for maintaining and distributing the contact force substantially uniformly across the contact array of the land grid array module and the contact array of the printed circuit board.

12. The mechanism of claim 11 wherein means for securing comprises at least one of:

an interposer disposed between the land grid array module and the printed circuit board;

a plurality of load posts extending through each of the land grid array module, the printed circuit board, the interposer, and the means for maintaining and distributing the contact force; and

a stiffening plate disposed on a side of the printed circuit board opposite the interposer and the land grid array module, and fixed to the load posts to be spaced from the printed circuit board.

13. The mechanism of claim 12 wherein the means for maintaining and distributing comprises:

a spring member disposed between the printed circuit board and the stiffening plate and having a first portion in contact with the backing plate and a second portion in pressing contact against the printed circuit board, wherein the spring member has a curved shape arranged to forcibly press against a center of the printed circuit board.

14. The mechanism of claim 13 wherein the second portion of the spring member comprises a central body portion and the first portion comprises a plurality of legs extending radially outward from the central body portion, with each leg having an end with a hole configured for receiving one of the load posts and the end configured for contact against the stiffening plate adjacent the load posts at each of a plurality of corners of the stiffening plate.

15. The mechanism of claim 12 wherein the means for securing a module comprises:

a plurality of load springs carried on the load posts and configured and positioned for exerting a compressive force on the land grid array module, the interposer, and the printed circuit board.

16. A method of distributing a contact force between a land grid array module and a printed circuit board, the method comprising:

securing the land grid array module to a first side of the printed circuit board via an interposer disposed on the first side of the printed circuit board and via a backing plate disposed on, and spaced from, a second side of the printed circuit board; and

biasing a curved spring member between the backing plate and the second side of the printed circuit board to insure a substantially uniform contact force across the module, the interposer, and the printed circuit board wherein a first portion of spring member is in secured contact with the backing plate and a second portion of the spring member is biased in unsecured, pressing contact against the second side of the printed circuit board.

17. The method of claim 16 wherein securing the land grid array comprises:

extending at least one load post through each one of four corners of the land grid array module, the interposer, the printed circuit board, and the backing plate; and

introducing, with a load spring mounted on each one of the load posts, a compressive force between the land grid array module, the interposer, and the printed circuit board.

18. The method of claim 16 wherein biasing a spring member comprises:

constructing the stiffening plate to include a recess for receiving and removably securing the first portion of the spring member on the stiffening plate.

19. The method of claim 16 wherein biasing the spring member comprises:

using the spring member to provide substantially all of a compressive force exerted on the land grid array module, the interposer, and the printed circuit board.